2SA2122

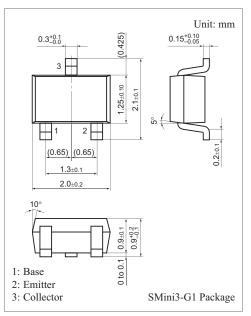
Silicon PNP epitaxial planar type

For general amplification Complementary to 2SC5950

Features

- \bullet High forward current transfer ratio h_{FE}
- Smini typ package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Unit Rating V Collector-base voltage (Emitter open) V_{CBO} -60 Collector-emitter voltage (Base open) V V_{CEO} -50-7 Emitter-base voltage (Collector open) V_{EBO} V Collector current I_C -100mА -200Peak collector current I_{CP} mA mW Collector power dissipation $P_{\rm C}$ 150 Ti 150 °C Junction temperature Storage temperature -55 to +150 °C T_{stg}



Marking Symbol: 7L

Electrical Characteristics $T_{ar} = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu {\rm A}, \ I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$	-7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -20 \text{ V}, I_{E'} = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$			-100	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	160		460	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$		-0.2	- 0.5	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_{E} = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_{EI} = 0, f = 1 \text{ MHz}$		2.2		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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